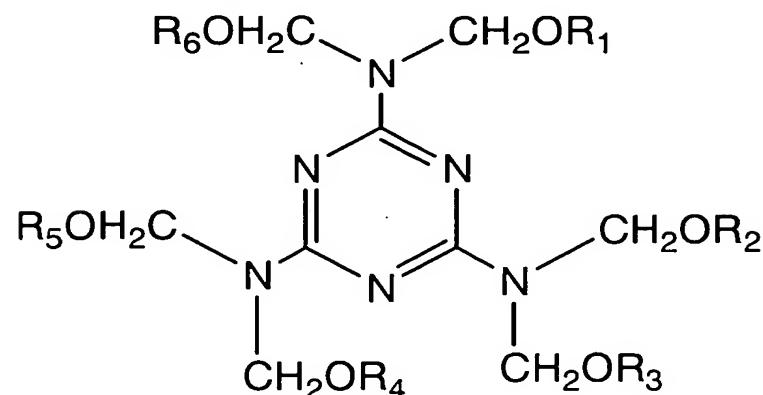


What is claimed is;

1. A positive photosensitive composition comprising a quinonediazide compound, a novolak resin, a compound reacting with the novolak resin by the action of an acid, and a compound generating an acid by heating.

2. The positive photosensitive composition according to claim 1, wherein the compound generating an acid by heating is a compound which is decomposed at 80 to 200°C to generate an acid.

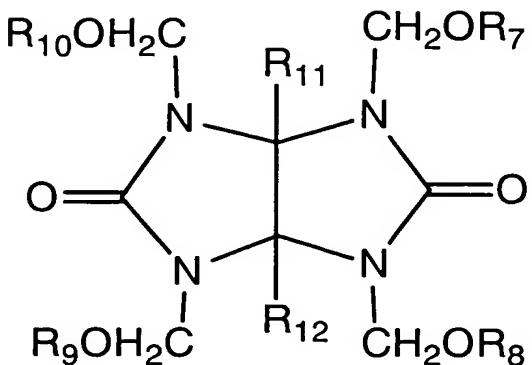
3. The positive photosensitive composition according to claim 1, wherein the compound reacting with the novolak resin by the action of an acid is at least one selected from the group consisting of compounds of the following formula (1) and compounds of the following formula (2).



(1)

(wherein, R<sub>1</sub> to R<sub>6</sub> each independently represent a

mono-valent organic group having 1 to 20 carbon atoms.).



(2)

(wherein, R<sub>7</sub> to R<sub>10</sub> each independently represent a mono-valent organic group having 1 to 20 carbon atoms, R<sub>11</sub>, R<sub>12</sub> each independently represent a hydrogen atom or a mono-valent organic group having 1 to 20 carbon atoms.).

4. A process for producing a pattern, wherein the process comprises the steps of applying the positive photosensitive composition according to claim 1 on a substrate, exposing the applied composition, developing the exposed portion, and hardening un-exposed portions by heating.

5. The process according to claim 4, wherein the pattern is a member of semiconductor or a member of display.